PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun Ying Lin	10/19/2007
Geng Shin Shen	10/19/2007
Yu Tang Pan	10/19/2007
Shih Wen Chou	10/19/2007

RECEIVING PARTY DATA

Name:	Chipmos Technologies Inc.	
Street Address:	No.1, R&D Rd. 1, Science-Based Industrial Park	
City:	Hsinchu	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11934287

CORRESPONDENCE DATA

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18506-100 ATTORNEY DOCKET NUMBER:

NAME OF SUBMITTER: Anthony King

Total Attachments: 2

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PATENT **REEL: 020060 FRAME: 0289**

ASSIGNMENT

WHEREAS, I (we), LIN, CHUN YING, SHEN, GENG HSIN, PAN, YU TANG, and CHOU, SHIH-WEN whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled LEADFRAME FOR LEADLESS PACKAGE, STRUCTURE AND MANUFACTURING METHOD USING THE SAME

(nereinance referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date
herewith unless at least one of the following is checked:
☐ United States Design Patent
was
executed on:
🗖 filed on: Serial No.:
established by PCT International Patent Application No.: filed: designating the United States of America
issued on as U.S. Patent No.:
WHEREAS, CHIPMOS TECHNOLOGIES INC.

whose post office address is NO. 1, R&D RD. I, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said Invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said Invention, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the Invention that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes any member of the firm of <u>WPAT, PC (Customer No. 60951</u> to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

Assignor Name	Address
LIN, CHUN YING	NO. 5, NAN-KO RD. 7, Science-Based Industrial Park, TAINAN COUNTY 744, TAIWAN, R.O.C.
Signature of Assignor Lin Chun Ying	Date of Signature 7007 / 10 / 19
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

PATENT REEL: 020060 FRAME: 0290

Assignor Name	Address
SHEN, GENG SHIN	NO. 5, NAN-KO RD. 7, Science-Based Industrial Park, TAINAN COUNTY 744, TAIWAN, R.O.C.
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Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

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PAN, YU TANG	NO. 5, NAN-KO RD. 7, Science-Based Industrial Park, TAINAN COUNTY 744, TAIWAN, R.O.C.
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Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name	Address
CHOU, SHIH WEN	NO. 5, NAN-KO RD. 7, Science-Based Industrial Park, TAINAN COUNTY 744, TAIWAN, R.O.C.
Signature of Assignor Shih-Wen, Chou	Date of Signature
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

PATENT REEL: 020060 FRAME: 0291

RECORDED: 11/02/2007